

## P-Channel 100 V (D-S) MOSFET

$V_{DS}$		-100	V
$R_{DS(on),typ}$	$V_{GS}=10V$	215	$m\Omega$
$R_{DS(on),typ}$	$V_{GS}=4.5V$	234	$m\Omega$
$I_D$		-9	A

### FEATURES

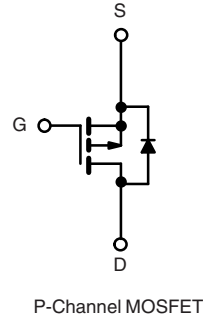
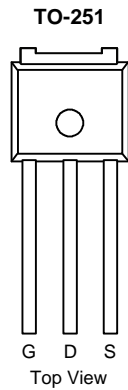
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 %  $R_g$  and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Power Switch
- DC/DC Converters



### ABSOLUTE MAXIMUM RATINGS $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	- 100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current ( $T_J = 150\text{ }^\circ\text{C}$ )	$I_D$	$T_C = 25\text{ }^\circ\text{C}$ - 9	A
		$T_C = 70\text{ }^\circ\text{C}$ - 8	
Pulsed Drain Current	$I_{DM}$	- 30	
Avalanche Current	$I_{AS}$	- 20	
Single Avalanche Energy <sup>a</sup>	$E_{AS}$	16.2	mJ
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_C = 25\text{ }^\circ\text{C}$ 32.1 <sup>b</sup>	W
		$T_A = 25\text{ }^\circ\text{C}^c$ 2.5	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 150	$^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) <sup>c</sup>	$R_{thJA}$	50	$^\circ\text{C/W}$
Junction-to-Case (Drain)	$R_{thJC}$	3.9	

Notes:

a. Duty cycle  $\leq 1\%$ .

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0\text{ V}$ , $I_D = -250\text{ }\mu\text{A}$	- 100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250\text{ }\mu\text{A}$	- 1		- 2.5	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$			$\pm 250$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -100\text{ V}$ , $V_{GS} = 0\text{ V}$			- 1	$\mu\text{A}$
		$V_{DS} = -100\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 125\text{ }^{\circ}\text{C}$			- 50	
		$V_{DS} = -100\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 150\text{ }^{\circ}\text{C}$			- 250	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \leq -10\text{ V}$ , $V_{GS} = -10\text{ V}$	- 15			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$ , $I_D = -3.6\text{ A}$		215		m $\Omega$
		$V_{GS} = -4.5\text{ V}$ , $I_D = -3.4\text{ A}$		234		
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -15\text{ V}$ , $I_D = -3.6\text{ A}$		12		S
Dynamic <sup>b</sup>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$ , $V_{DS} = -50\text{ V}$ , $f = 1\text{ MHz}$		1300		pF
Output Capacitance	$C_{oss}$			65		
Reverse Transfer Capacitance	$C_{rss}$			41		
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{DS} = -50\text{ V}$ , $V_{GS} = -10\text{ V}$ , $I_D = -3.6\text{ A}$		23		nC
				11		
	$Q_{gs}$	$V_{DS} = -50\text{ V}$ , $V_{GS} = -4.5\text{ V}$ , $I_D = -3.6\text{ A}$		3.5		
				4.8		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$					
Gate Resistance	$R_g$	$f = 1\text{ MHz}$	1.2	5.7	11.5	$\Omega$
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = -50\text{ V}$ , $R_L = 17.2\text{ }\Omega$ $I_D \cong -2.9\text{ A}$ , $V_{GEN} = -10\text{ V}$ , $R_g = 1\text{ }\Omega$		7	14	ns
Rise Time <sup>c</sup>	$t_r$			12	18	
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$			33	50	
Fall Time <sup>c</sup>	$t_f$			9	18	
Drain-Source Body Diode Ratings and Characteristics $T_C = 25\text{ }^{\circ}\text{C}$ <sup>b</sup>						
Continuous Current	$I_S$				- 8.8	A
Pulsed Current	$I_{SM}$				- 15	
Forward Voltage <sup>a</sup>	$V_{SD}$	$I_F = -2.9\text{ A}$ , $V_{GS} = 0\text{ V}$		- 0.8	- 1.5	V
Reverse Recovery Time	$t_{rr}$	$I_F = -2.9\text{ A}$ , $dI/dt = 100\text{ A}/\mu\text{s}$		50	75	ns
Peak Reverse Recovery Current	$I_{RM(REC)}$			- 4	- 6	A
Reverse Recovery Charge	$Q_{rr}$			98	147	nC

Notes:

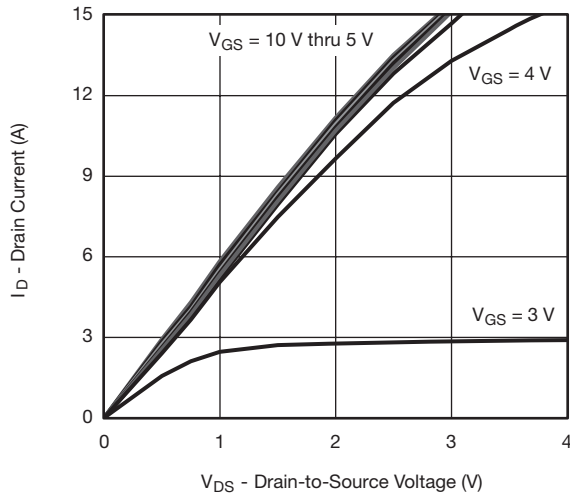
a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

b. Guaranteed by design, not subject to production testing.

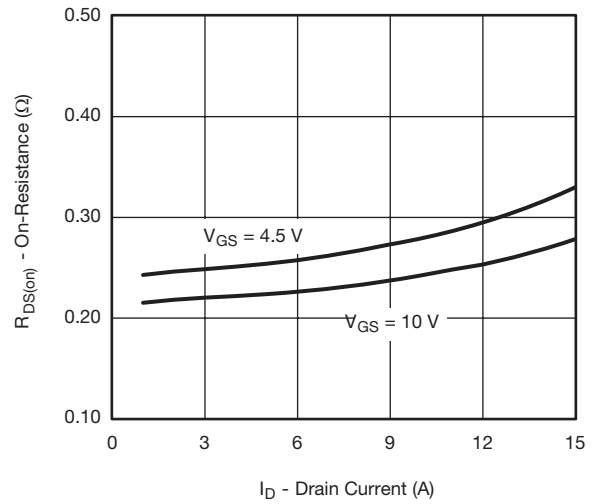
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

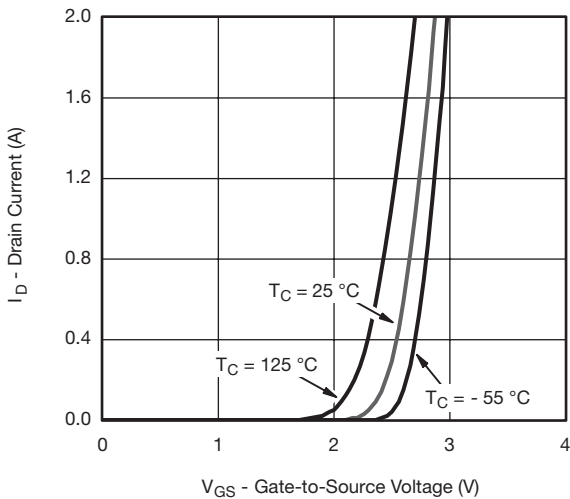
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



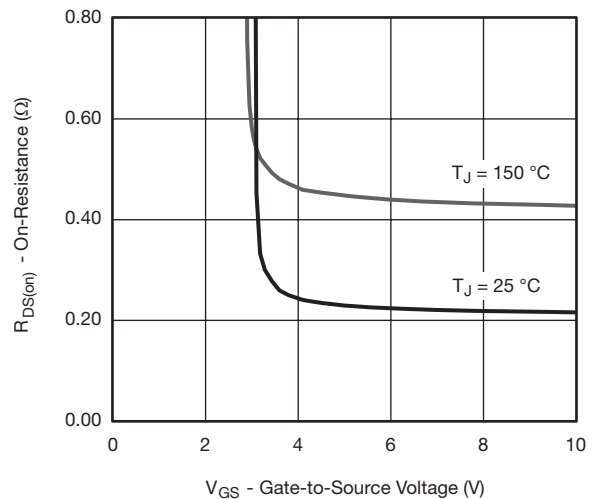
**Output Characteristics**



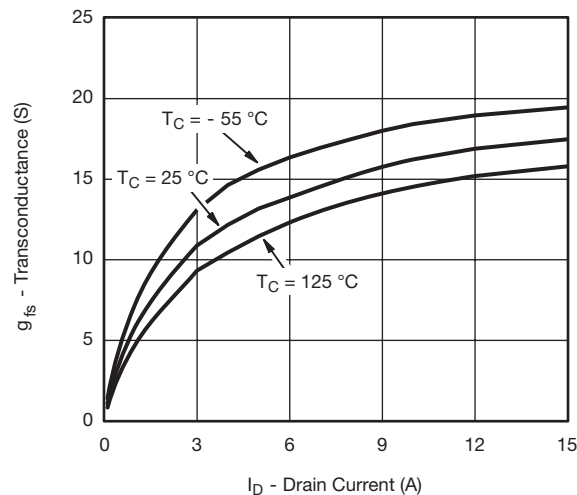
**On-Resistance vs. Drain Current**



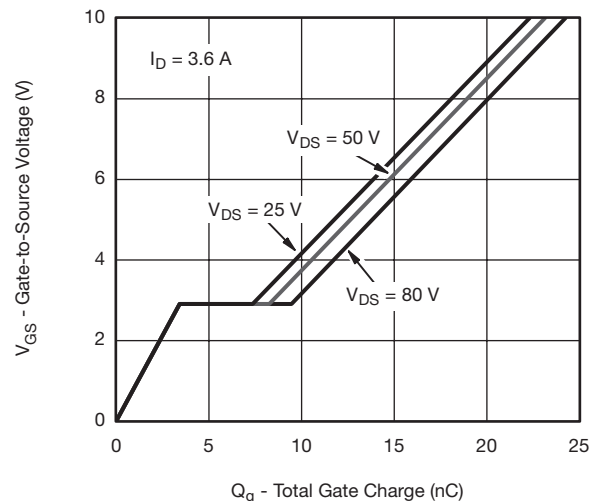
**Transfer Characteristics**



**On-Resistance vs. Gate-to-Source Voltage**

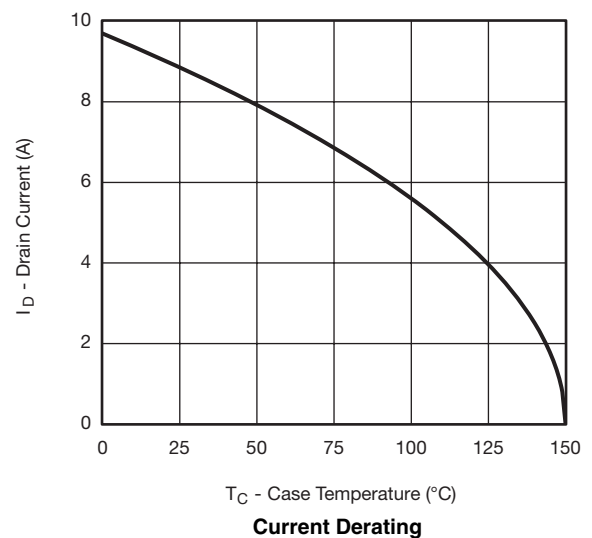
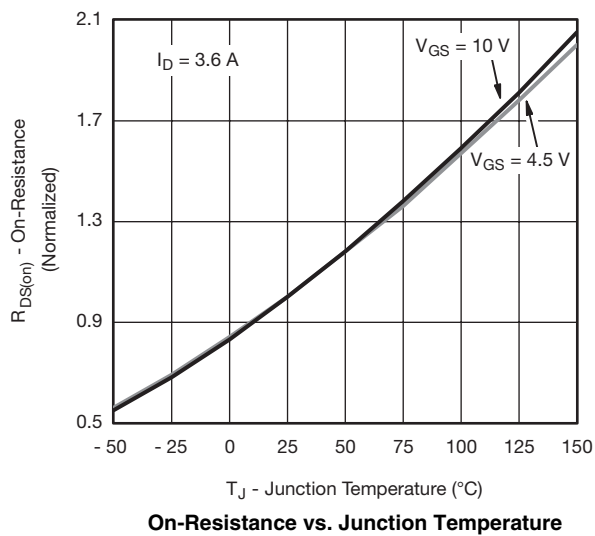
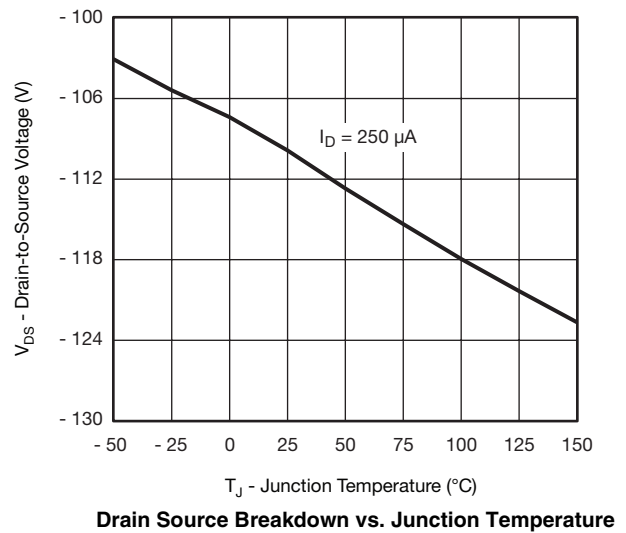
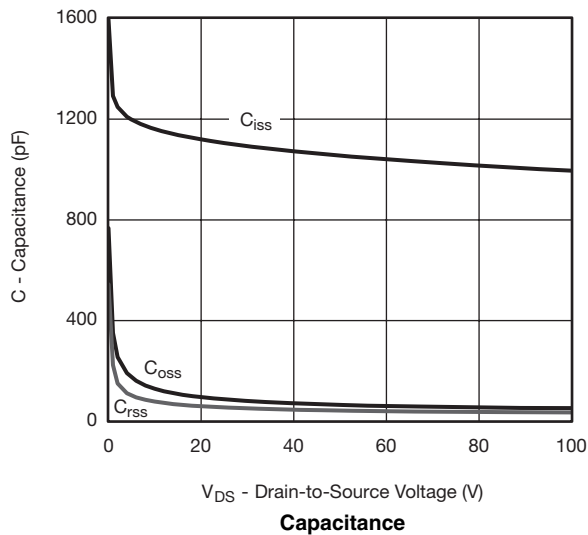
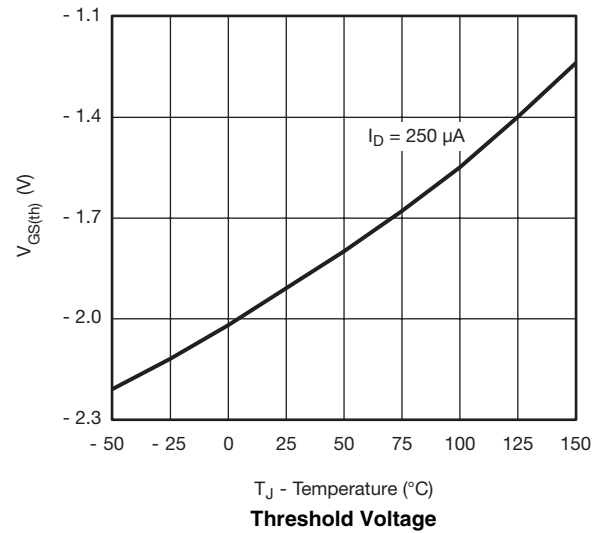
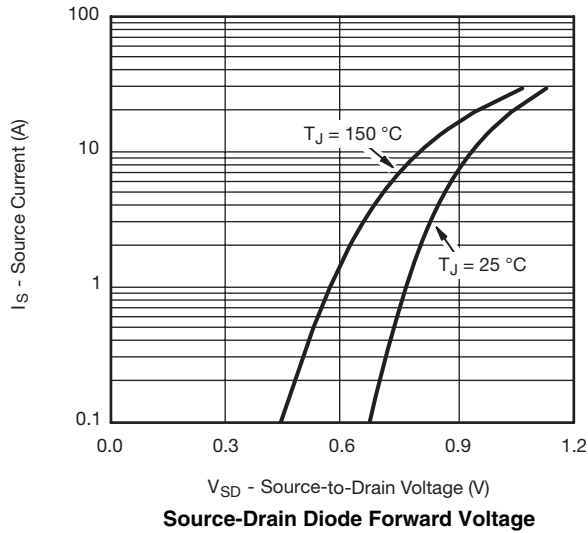


**Transconductance**

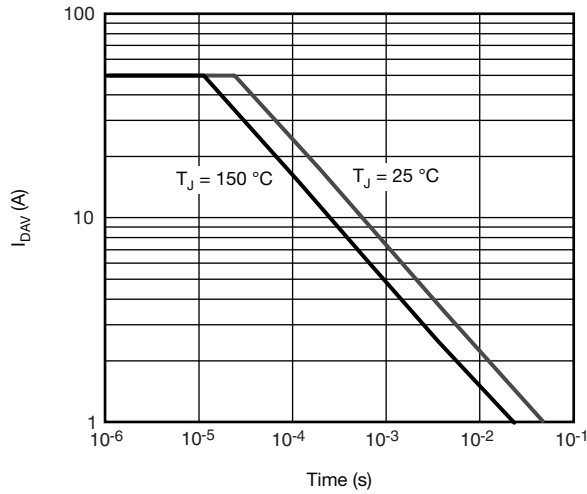


**Gate Charge**

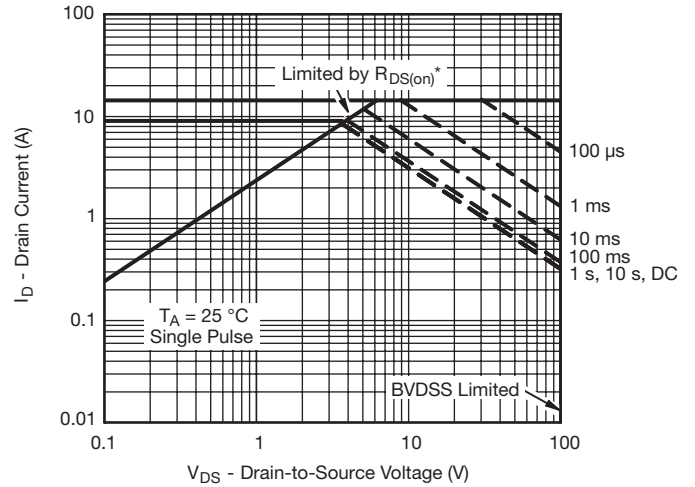
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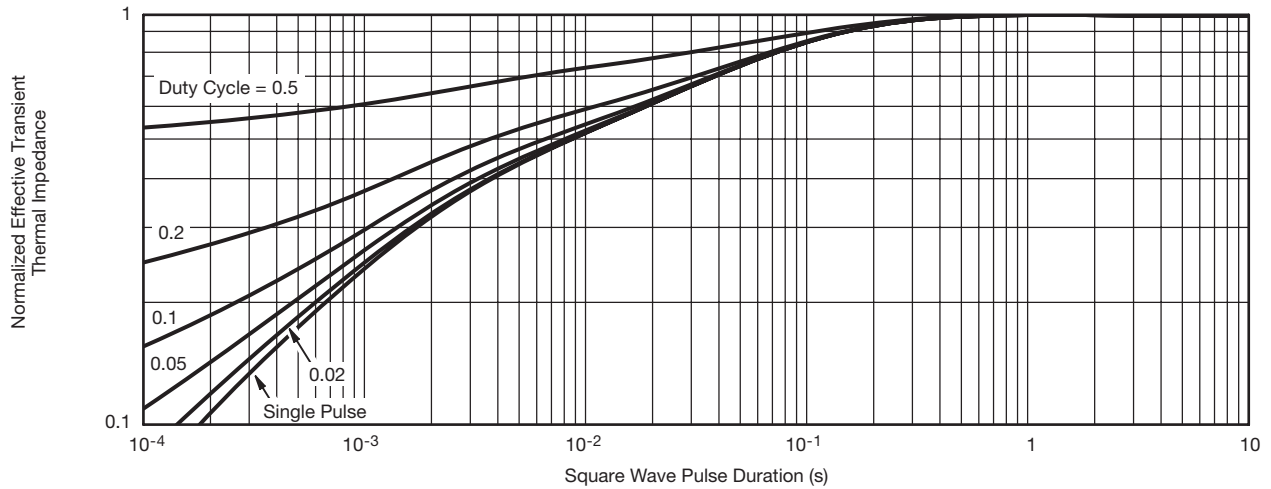


Single Pulse Avalanche Current Capability vs. Time



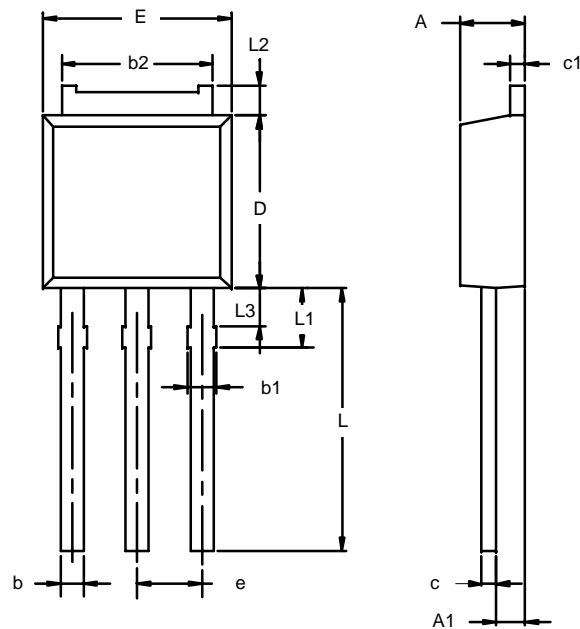
\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

TO-251AA P AK



Note: Dimension L3 is for reference only.

Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
c	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
E	6.48	6.73	0.255	0.265
e	2.28 BSC		0.090 BSC	
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346				

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